



Turn-key Product Engineering &
Electronics Manufacturing



Rapidise Capabilities Deck For



We are **transforming the ODM landscape**
by seamlessly connecting design and
manufacturing with our cutting-edge on-
demand platform

Our USP

- 25+ yrs of Manufacturing Services Delivery
- 12+ Yrs of Design Services Delivery
- Owned Manufacturing & Assembly Line
- Electronics, Mechanical, IoT, AI & Cloud Development
- Ready Products for White-labelling

Manufacturing &
Engineering Team

300+

SMT & PCBA Facilities

2

Successful
Product Deliveries

135+

Full Product Assembly &
Testing Lines

6

Satisfied
Customers

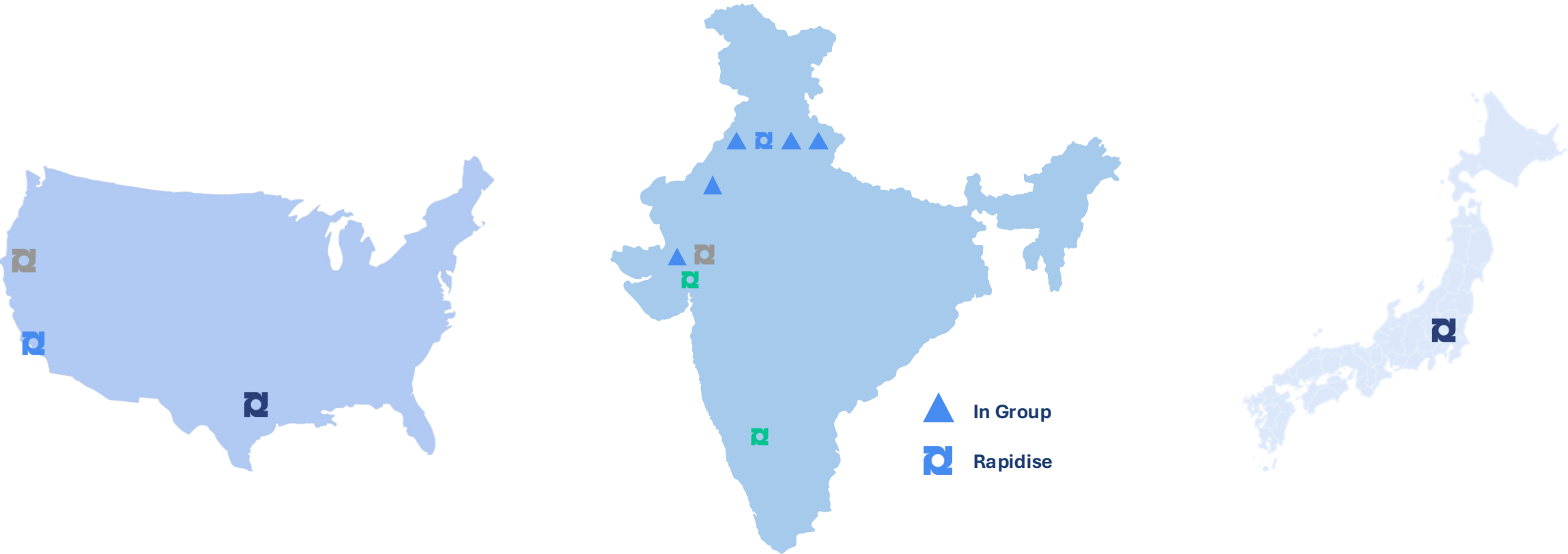
100+

R&D, Development & Product
Testing Centers

3



Global Footprint:



- 1 Manufacturing Facility
- 1 Sales Offices
- 1 USA HQ



- 3 R & D Centers
- 9 Manufacturing Facilities
- 1 India HQ



- 1 Sales Office



Sample A

Prototype / Pre-production Samples)

Key Deliverable

- Architecture Documentation & Blueprints
- Sample A -Prototype

Key Results:

- Design Version 1.0
- Architecture with Test Cases & Acceptance Criteria
- Component Selection & Bill Of Materials(BOM)
- PCB Schematic, Layout & Gerber Files
- Mechanical Design CAD Files

Sample B

Engineering Sample / Pre-Production Sample)

Key Deliverable

- Engineering Sample, DFM Prototype
- Sample B – Prototype with Multiple Units Testing

Key Results:

- Design Version 2.0
 - Corner Cases
 - Ensuring Operational Safety on Board Level
- DFM/ DFA
- Verify compliance with safety standards and regulations.
- Multiple Units Testing – Functional Testing at Hardware Level

Sample C

Production Validation Sample)

Key Deliverable

- Sample C –Prototype

Key Results:

- Reliability Test, EMI/EMC
- Temperature Endurance Testing
- Evaluate Manufacturing Process & Tooling
- HALT / HAST Tests
- Automated Testing Zig

Sample D

Production Samples

Key Deliverable

- Production – Documentation release

Key Results:

- Design Version 4.0 :
 - Field Testing
 - Performance Improvement
- Final Design For Manufacturing (DFM) Changes
- Final Manufacturable Design Files Injection Molded Enclosure

Manufacturing / Production Level

Key Deliverable

- Fully Commercialized Product (2000 Units)

Key Results:

- Product Manufacturing & Assembly
- Component Supply Chain Management
- Packaging & Shipping
- Ongoing QA/QC Testing



Product Engineering Service

- Embedded Hardware
- Embedded Software
- AI Development
- Information Technology (Web, Cloud Engineering, Mobility)
- Mechanical Design
- New Product Introduction

- IP - Accelerators

- SOM
- SBC
- SDK



- Telep AI Models

Electronics Manufacturing Service

- Supply Chain Setup & Procurement
- PCB Fabrication
- PCBA (SMT, DIP, TH)
- Cables & Wire Harness
- Mold Manufacturing
- Enclosure Manufacturing
- Automated & Manual Product Testing
- Product Assembly
- Packaging & Logistics

ODM Marketplace

- Ready Products
 - Beacons
 - Data Loggers
 - BLE Tags
 - Edge AI Box
 - Dash Camera
 - LTE Camera
 - Body Camera



- Strategic Revenue Driver towards ODM / OEM



Embedded Hardware

- Hardware Architecture
- BoM Optimization
- Electrical Schematic Design
- Multilayer PCB Layout Design
- High-Speed Board Design
- Analog & RF Design
- Certification & DFM
- Image, Audio, Antenna Tuning



AI Development

- Computer Vision
- Edge Computing & AI
- Algorithm Development
- Recommendation Engine
- Natural Language Processing
- ADAS & DMS
- Healthcare AI
- Predictive Maintenance



Mechanical Design

- New ID concept generation
- Product Design & Development
- Reverse Engineering & Concept designing
- Simulation and Analysis
- IP Standards Validation
- 3D Engineering



Embedded Software

- Bare Metal, RTOS, Linux, AOSP
- BSP, Device Driver and Firmware
- Linux Kernel Customization
- HAL, I2C, SPI, PCIe, WiFi, Cellular, Sensors
- Multimedia Codec & Framework
- FOTA - Firmware Over the Air
- User Interface Software



Information Technology

- Web & Mobile App Development
- API Development and integration
- IoT Dataflow Architecture
- Data Visualization
- Managed DevOps Services
- Cloud Engineering - AWS, Azure, GCP
- Robotic Process Automation
- Metaverse, AR/VR App



New Product Introduction

- Certifications
- DFM Analysis
- Supply Chain Management
- Automated Test Jigs
- Feature Enhancing and Re-engineering
- BOM Optimization
- Performance Optimization



Manufacturing Services

- Electronic Design Validation
- PCB Assembly (SMD, DIP, TH)
- Supply Chain & Sourcing
- Mold & Enclosure Manufacturing
- Prototyping
- Box Build & Full Product Assembly
- QA/QC & Testing
- Packaging
- Green Manufacturing



Manufacturing Capabilities

- Manufacturing & Engineering Team of 500+
- 10 Electronics Manufacturing & PCBA Facilities
- 18 SMT & 22 Full Product Assembly Lines
- 6 R&D and Final Product Testing Centers
- SMT Area Rated Class 100,000 Clean Room
- Camera Module Assembly Area Rated Class 100,000 Clean Room
- Solder Paste Printer
- In line Solder Paste Inspection (Make: Kohyoung)
- Nitrogen and Lead-free Compatible Soldering
- Wave Soldering
- Selective Soldering (Make: ERSA)
- Pin Insertion Machine (Make: TE P350)
- Inspection- 3D Automatic Optical (Make: Omron)
- Inspection- In-line X Ray Machine (Viscom (Germany) and Shimadzu (Japan))
- PCB Cleaning (Make: Unitech)
 - Electromagnetic Testing (EMI & EMC), ESD (Electrostatic) Control workstation
 - Thermal, Humidity, Insulation Testing, Endurance & Ageing Testing
 - Climatic Chambers (Hot, Cold and Humid)
- Component mounting machine Capability:
 - Min : 0402mm/ 03015 inch
 - Max : 102*102*T 25.4 mm
 - Accuracy : 30 Micron

Services - Product Reliability Test Lab :



EMI Testing

- Electro Magnetic Interference
- ESD checker system
- ESD Simulator
- Semi Anechoic Chambers:
- EMI Test Receivers:
- RF Power Amplifiers:
- Pre-Amplifiers
- Antennas
- Directional Couplers
- BCI Probes



IP Rating

- Air Showers
- Bench Top Environmental Chamber
- Temperature & Humidity Test
- Salt Spray Chamber
- Dust Chamber
- Water Spray
- Thermal Shock
- Vibration Test
- Transient Voltage
- Laboratory Oven



RF Tuning

- Spectrum Analyzers
- Vector network Analyzers
- Signal Generators
- RF and Microwave Switches



Vehicle Testing

- Vehicle Cold Chamber
- Chassis Dynamometer



EPC Testing

- 100x Microscope
- Profile Tuning Suite
- ESD protected production floors
- Electro-Static Discharge
- Dark Room for camera lens calibration
- Resistance Meter
- Power Analyzer
- Thermal Imager
- Function Generator
- Insulation Test
- Electronic Lead Test
- LCR Meter
- Highly Accelerated Stress Test
- Switch Endurance
- Oscilloscope
- ACG Rig Test Bench (Vehicle Simulation)
- Digital Call Box and Analog Call Box



Water Spray Chamber



Salt spray & Thermal Shock



Accelerated Stress Test



Hot / Cold Environment Chamber



MID Motor Performance Test Rig



Sensor Functional Tester




Performance Measurement




EMI-EMC


Camera (Tejas)




LTE Edge AI LTE
Camera 12 TOPS




WiFi Edge AI LTE
Camera 48 TOPS



LTE Edge AI LTE
Camera 8 TOPS




WiFi Camera




Video
Doorbell


Dashcam



LTE Dashcam




WiFi Dashcam




Edge AI Dashcam


Edge AI Bodycam 8TOPS



LTE Bodycam



5G Bodycam



WiFi Bodycam

Trackers (Tekt)

Beacon



Lite N1



Pro N4

Safety



Tejas Safety Lite



Tejas Safety Pro



Smart Helmet



Smart Hook

Gateway / HMI (RISE)



AI Box 12 Tops



AI Box 8 Tops



8 TOPS HMI



SBC 6125



SOM 6490



SOM 5430



LTE Gateway
2 TOPS



Career Board for
6490/5430



SOM 8550



Career Board
For 8550

IOT and Connected Devices



Security Devices

Office Devices

Automotive Devices

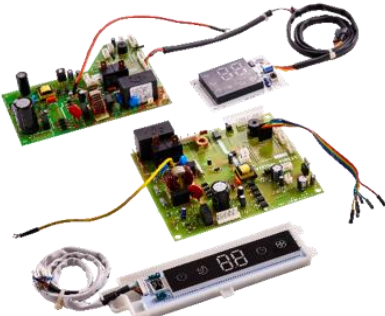
Health Devices

Home Devices

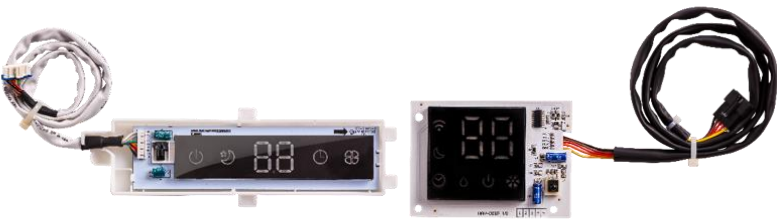
Industrial Application Controller / Controllers for Fans & Air Conditioners



Brushless DC Fan Controller



Internal Display Unit PCB



Internal Display Units (IDU)



Outdoor Unit PCB Assembly

Deliveries Across Industries Served :

Automotive



ADAS Camera



DMS Camera



Infotainment System



Vehicle Tracker



Location Tracker



Telematics



Instrument Cluster



Battery Management System



ECU

Consumer Electronics



Smart Watch



Personal Tracker



Smart Headphone



Smart Speaker



Smart Wi-Fi Plug



Smart Mailbox



Laptop



Mobile



Smart Farming Device



Smart Grain Monitoring

Healthcare & Fitness



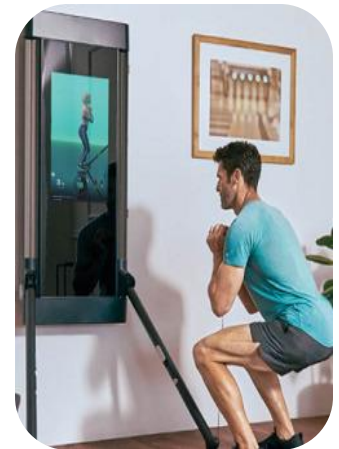
Fitness tracker



Smart headband



Smart Skin Care



Smart Trainer



Smart Yoga Mat



Smart Lap Counter



Smart Wound Care

Security & Surveillance



VMS System



Tejas Safety



Surveillance Camera



Smart BLE Lock



Smart Access Control System



LoWRA Gateway



Wi-Fi Door Bell

Value Proposition For Free2Move





Free2move eSolutions, a Stellantis and NHOA joint venture, provides innovative electric vehicle charging solutions

https://www.esolutions.free2move.com/eu/en_it/

RAPIDISE

EV Data Logger

VSaaS Platform

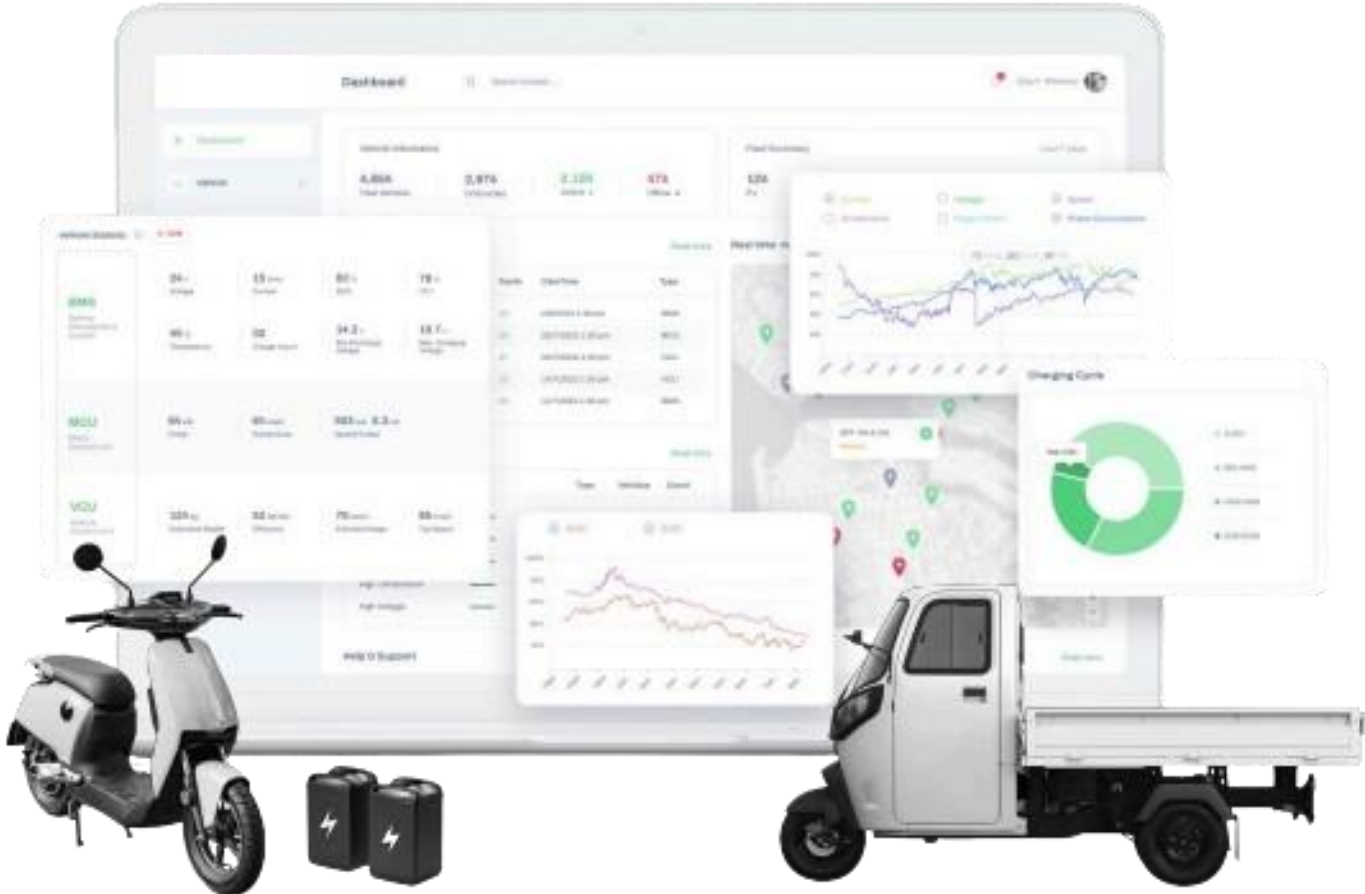
Edge AI Box

HMI Expertise

EV Data Logger Product



Product Image



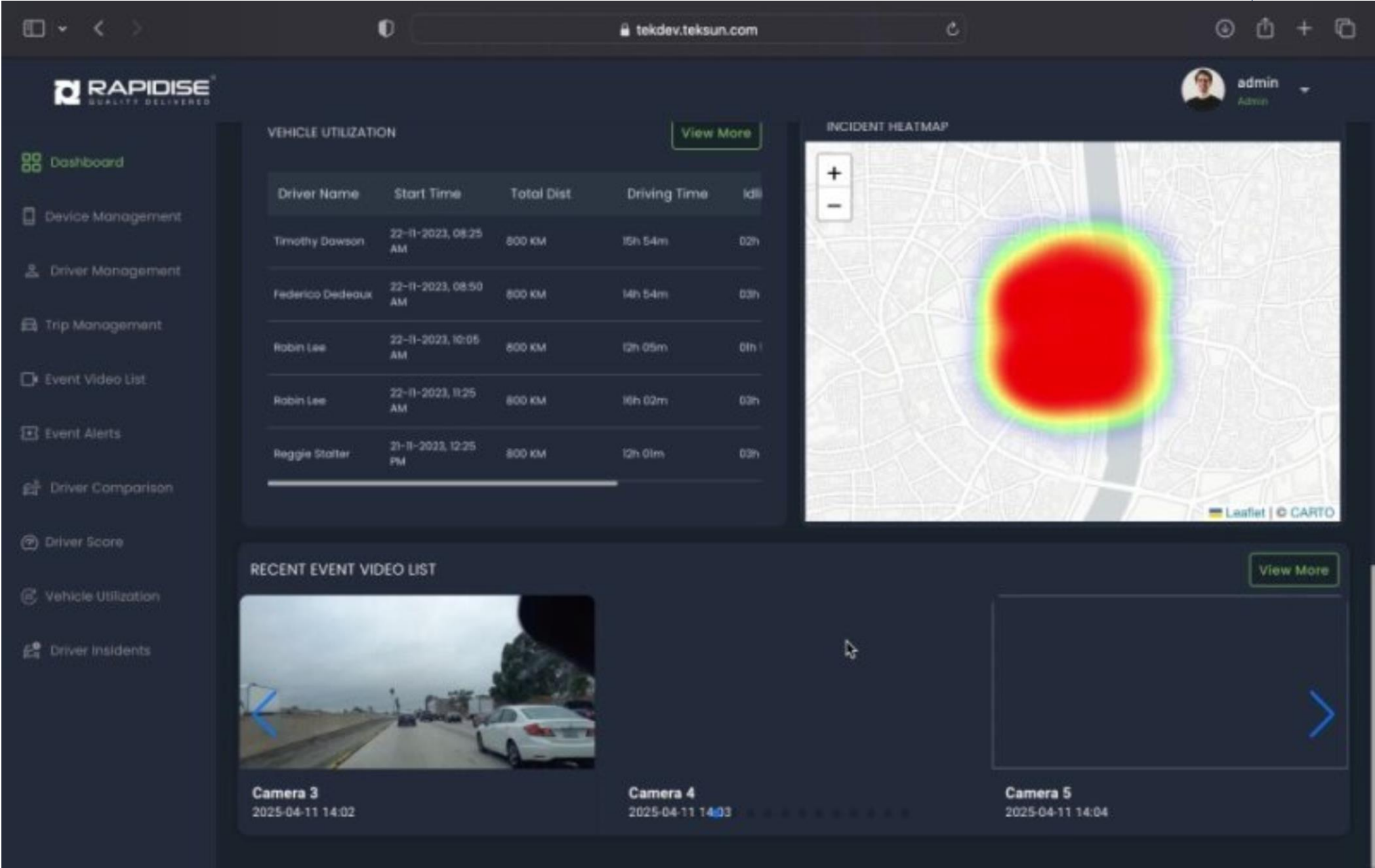
Technical Specifications – EV Data Logger

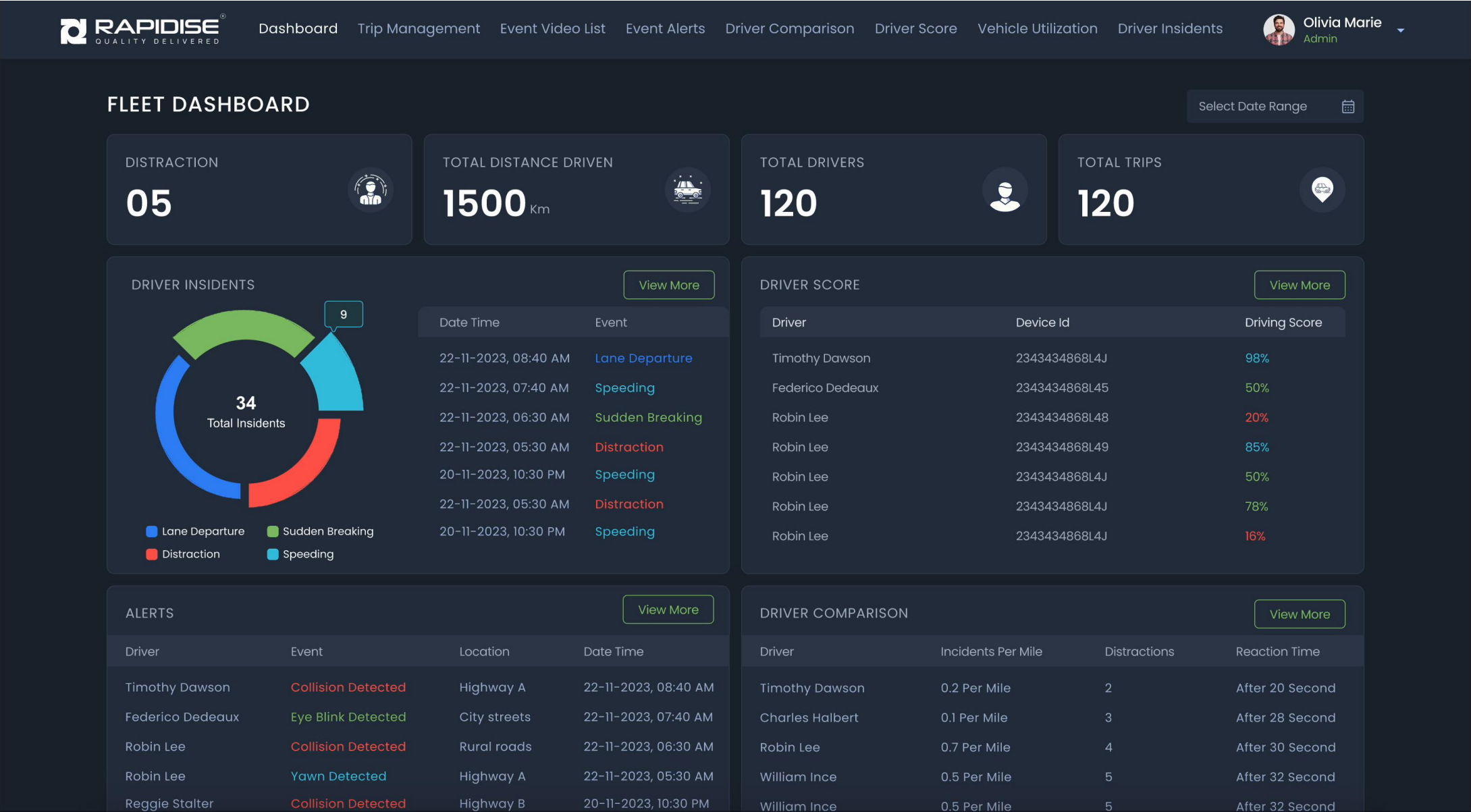
Module	
Product	Sarathi 1 Version 3.0
Technology	GSM/GPRS/GNSS/CAN 2.0
Color	Black
CAN Speed	50, 100, 125, 200, 250, 333, 500, 625, 833, 1000
GNSS	
GNSS	GPS, GLONASS, IRNSS, BEIDOU, QZSS, BDS
Receiver	33 Channel
Autonomous Acquisition	-148 dBm
Position Velocity	< 1.8 m CEP
Velocity Accuracy	< 0.03 m/sec
Communication Protocol	
CAN	CAN 2.0 A and CAN 2.0 B
External Memory	
External Memory Size	8 MB
Cellular	
SIM	Micro SIM
Technology Band	GSM/GPRS : 2G/4G
Data Transfer	GPRS
Data Support	SMS
Antenna	GSM (FPC)

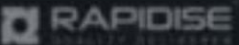
Features	
GNSS	GPS, GLONASS, IRNSS, BEIDOU, QZSS, BDS
Sensors	6 – Axis IMU (Accelerometer & Gyroscope)
Sleep Mode	Online Deep Sleep, Deep Sleep
Diagnostics and FOTA	FOTA Supported
GPIO	4 DI/DO, 1 AI/AO
LED Indication	3 LEDs
Other Features	Offline Data Storage Internal GPS Battery Backup
Power	
Input Voltage Range	6 – 90VAC with Reverse Voltage Protection
Physical Specifications	
Dimensions	110mm x 40mm x 15.5mm
Operating Environment	-35°C to +75°C

VSaaS Platform









Dashboard

Device Management

Service Management

User Management

Tracking Manage

File Management











Subscription Plan

Plan History

My Profile

Device Manag

Search

Sr.	MAC A	MAC Address*	Device Name*	Added on	Action
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2	C8:F7:E	Select Service*	Device Type	04-11-2024, 12:25 PM	 
3	dc:a3:5	Telep ADAS	IOS	17-10-2024, 15:21 PM	 
4	dc:a3:5	Select Users	Package Name	17-10-2024, 14:47 PM	 
5	dc:a3:5	Pragnesh Hardik	iphone1.0	06-08-2024, 11:16 AM	 

IMEI Field

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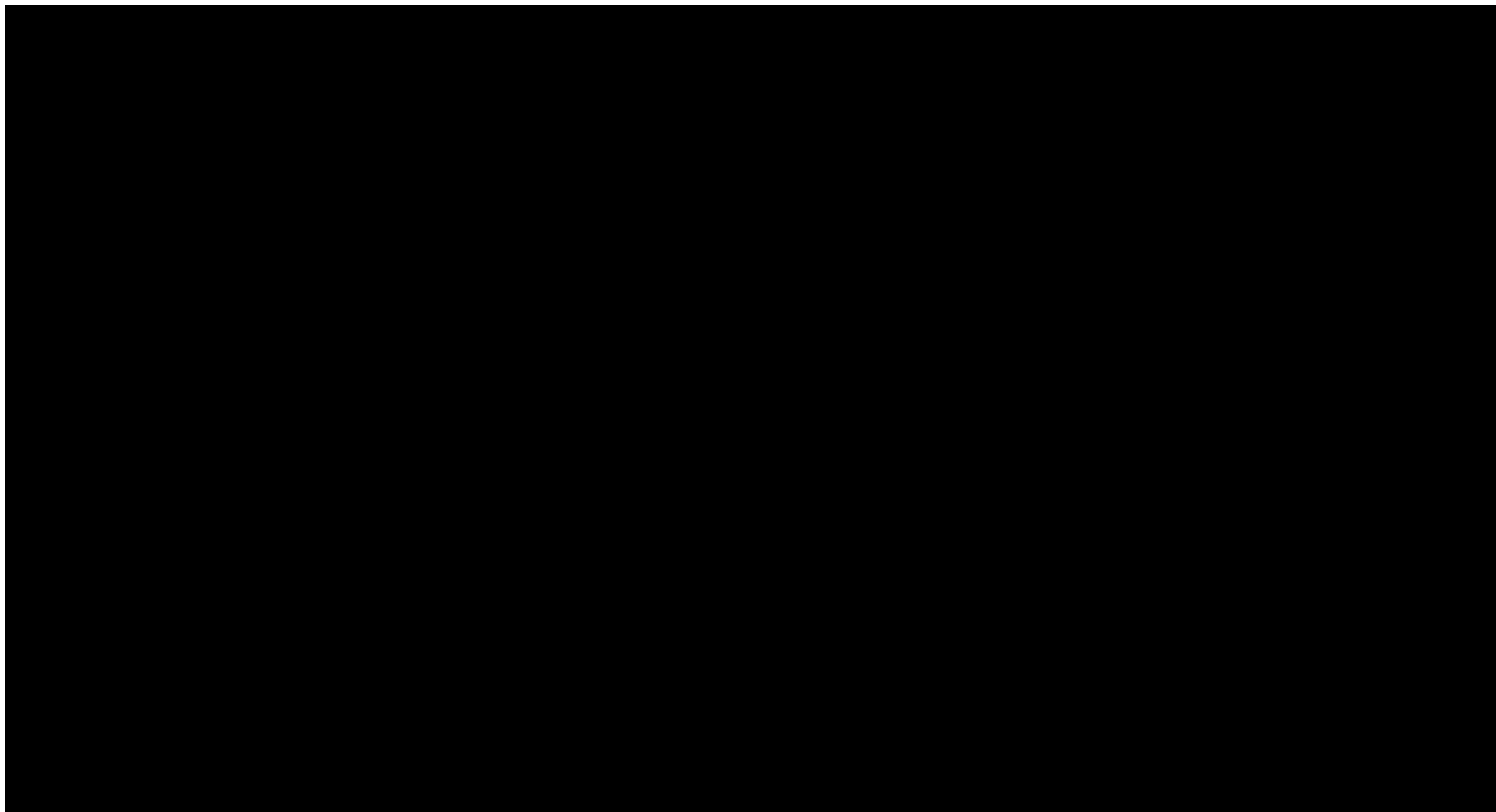
IMEI number must be 15 digits

CancelAdd

1:37

RSP3 - Rapidise Edge AI Processing Platform



Rapidise ODM Products and Roadmap



RISE Series Smart IoT Module Roadmap

EDGE COMPUTING
SMART CAMERA
AUTONOMOUS VEHICLES
AUTONOMOUS MOBILE ROBOTS (AMR)
VIDEO CONFERENCE
CLOUD GAMING

EDGE COMPUTING
AUTOMOTIVE
INDUSTRIAL ROBOT
DIGITAL SIGNAGE
RUGGED TABLET/HANDHELD DEVICE
HEALTH CARE
SMART WEAR/HOUSING

EDGE COMPUTING
RETAIL
AGRITECH
SECURITY SURVEILLANCE

INDUSTRIAL AUTOMATION
SMART CITY
HEALTHCARE
ROBOTICS

AUTOMOTIVE
RETAIL
HEALTH CARE
ROBOTICS

CPU 8 Core
DSP 4 Core
NPU 48 Tops
GPU 719 MHz
ISP Triple (108MP)



Drones Real-time Object Tracking
Military Low Light Camera Vision
Defense Environment Monitoring

Q4

CPU 8 Core
DSP 2 Core
NPU 12 Tops
GPU 812 MHz
ISP Triple (58MP)



Automotive Pedestrian Detection, Multi-Class Vehicle Detection
Smart Infra Real-time Incident Detection, Over Speed Detection
Healthcare SPO2, Heart Rate, Blood Pressure, Bilirubin

Q3

CPU 8 Core
DSP 2 Core
NPU 8 Tops
GPU 550 MHz
ISP Triple (58MP)



Surveillance Face Recognition, Gun Detection, Tailgating
Automotive Lane Departure, Blind Spot, Seat Belt
Agritech Crop Health, Soil Analysis

CPU 8 Core
DSP 2 Core
NPU 5 Tops
GPU 315 MHz
ISP Dual (44MP)



Industrial IoT PPE Compliance, Product Assembly QC
Smart City Signal-Light Violation Alerts, Light Traffic Analytics, ANPR
Healthcare Fall Detection, Patient Monitoring

2.25

CPU 6 Core
DSP 2 Core
NPU 3.5 TOPS
GPU 315 MHz
ISP Dual (44MP)



Automotive Driver Drowsiness, Blink Detection, Forward Collision
Retail Smart Shelf Stock Alerts, Heatmap
Healthcare Basic Mask Detection, rPPG HR Estimation

Q2

3.5 TOPS

5 TOPS

8 TOPS

12 TOPS

48 TOPS

RISE C1 Series Module Roadmap

AUTOMOTIVE
LEGAL & INSURANCE
SAFETY & SECURITY
ANALYTICS & AI
FLEET & LOGISTICS

AUTOMOTIVE
ROBOTICS & MACHINERY
PROCESS CONTROL

HEALTHCARE
TRAFFIC CAM
INDUSTRIAL & FIELD WORK
TRANSPORTATION

INDUSTRIAL AUTOMATION
SMART CITY
SECURITY
SMART HOTEL

AUTOMOTIVE
SECURITY
ROBOTICS

Dashcam
CPU 8 Core
DSP Hexagon™
NPU 1.1 TOPS
GPU 950 MHz
ISP Dual(16+24)



Automotive Surveillance
Legal Evidence, Verification
AI Analysis, Prediction

HMI
CPU 8 Core
DSP Hexagon™
NPU 1.1 TOPS
GPU 950 MHz
ISP Dual(16+24)



Automotive Navigation, Infotainment, Telematics
Robotics & Machinery Command, Calibration, Execution
Process Control Supervision, Feedback, Alarm

Body Camera
CPU 8 Core
DSP Hexagon™
NPU 1.1 TOPS
GPU 950 MHz
ISP Dual(16+24)



Traffic Cam Vehicle tracking, Car Accident Witness, Evidence
Healthcare Monitoring, Protection, Triage
Industrial & Field work Inspection, Auditing, Repair
Transportation Navigation, Validation

LTE Camera
CPU 8 Core
DSP Hexagon™
NPU 1.1 TOPS
GPU 950 MHz
ISP Dual(16+24)



Industrial IoT PPE Compliance, Product Assembly QC
Smart City Signal-Light Violation Alerts, Light Traffic Analytics, ANPR
Healthcare Fall Detection, Patient Monitoring
Security Theft Alert, Home Surveillance

RISE C1
CPU 8 Core
DSP Hexagon™
NPU 1.1 TOPS
GPU 950 MHz
ISP Dual(16+24)



Automotive Driver Drowsiness, Blink Detection, Forward Collision, Car Accident Witness
Security Home Surveillance, Alarms

Q4

Q3

Q2

RISE C1

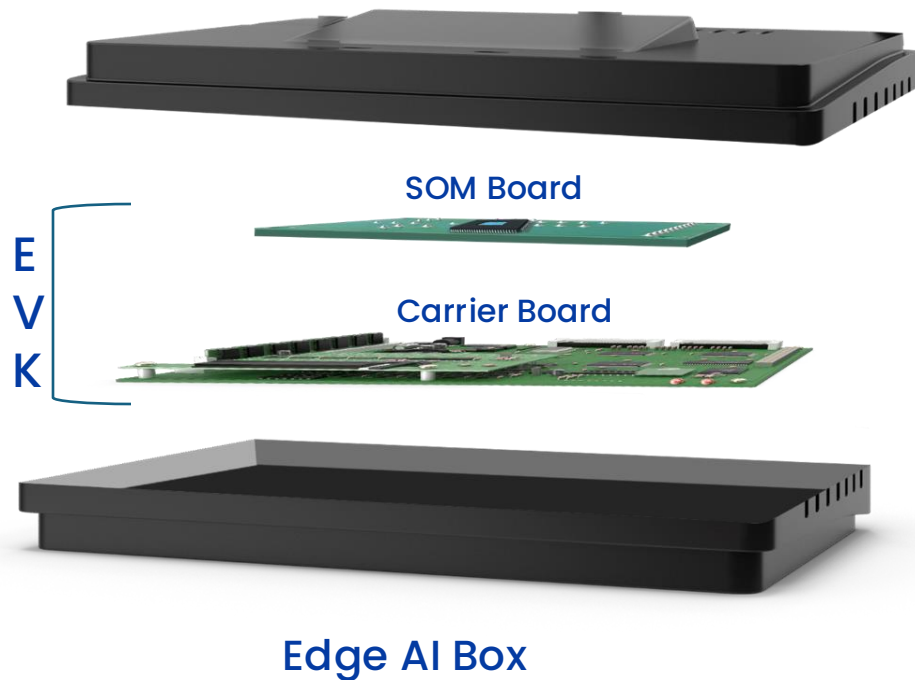
LTE CAMERA

BODY CAMERA

HMI

DASH CAMERA

RISE Edge AI Multimedia Box



Platform

SOC - Qualcomm QCS6490
CPU - Qualcomm® Kryo™ 670
GPU - Qualcomm® Adreno™ 643L
Video Processor - Adreno VPU 633
System Memory - RAM 8GB
NPU: 12 TOPS
Android OS

Wireless Connectivity

WiFi + BLE - Inbuilt Support for
Wi-Fi + BLE
4G - Support M.2 3042 4G/3052
(4G module optional)

Interfaces

USB | Ethernet | COM Port | DI/DO

Display Interfaces

1 x HDMI OUT | 1 x DP V1.4 (Over Type-C)

Audio Interfaces

1 x Speaker OUT | 1 x HDMI IN AND 1 x
HDMI OUT with Audio (Over I2S interface)

Camera Interface -

3 x 4-lane D-PHY Camera, 2 x GMSL

Storage

Flash - 128GB eMMC

Expansion - SD Card, M.2 2280 SSD NVMe

Industry 4.0

Product Inspection
Shorting
Predictive Maintenance
Workforce Safety
Energy Management
Productive Measurement

Retail Industry

Head Count
HeatMap
Demographic Analysis
Suspicious Behaviour Identification
Face Recognition

Healthcare

Heart Rate
Blood Oxygen (SPO2)
Physiotherapy
Fall Detection
Worker Stress Monitoring

Traffic

Automatic Number Plate Recognition
Vehicle In Out Monitoring
No Helmet
No Parking

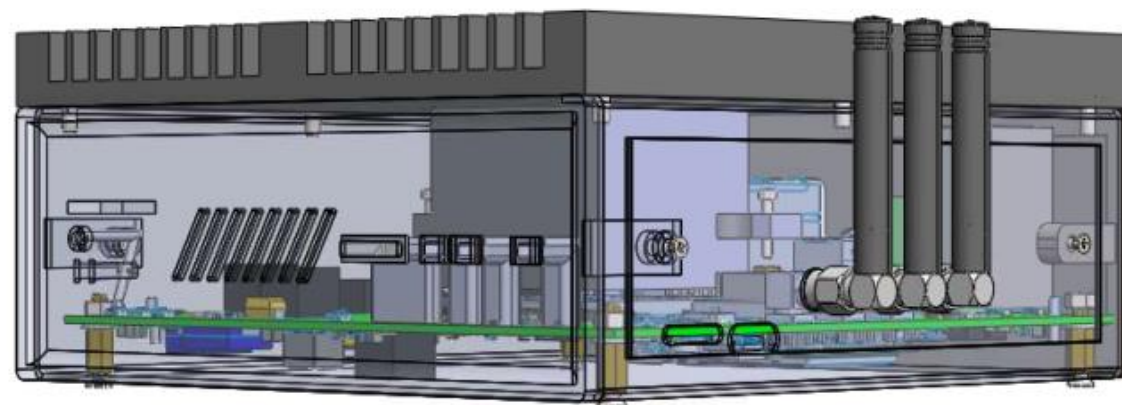
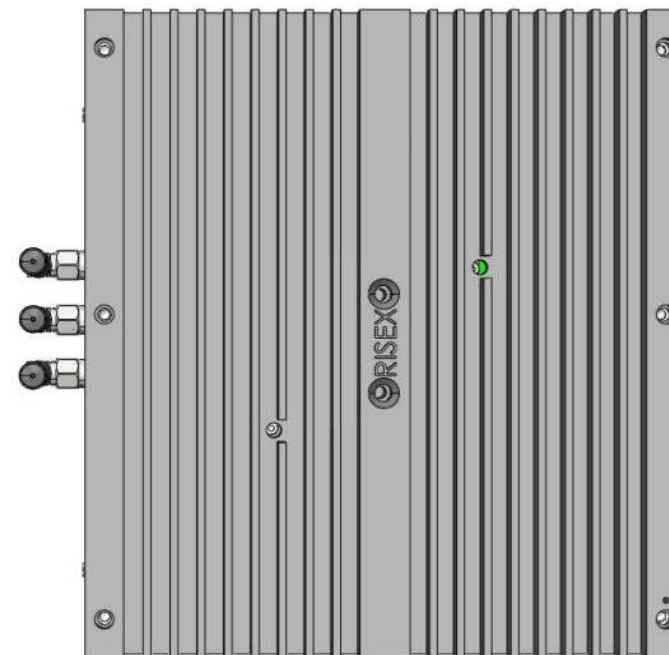
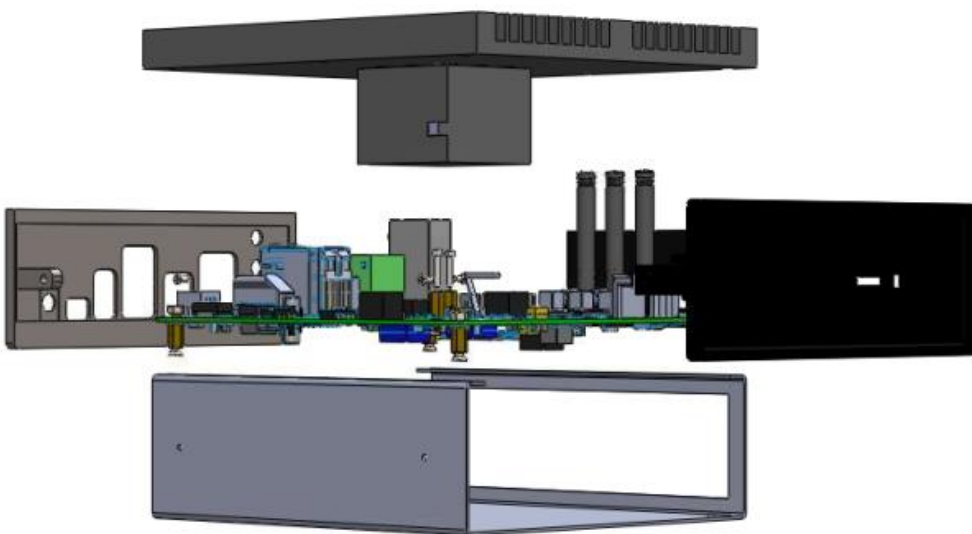
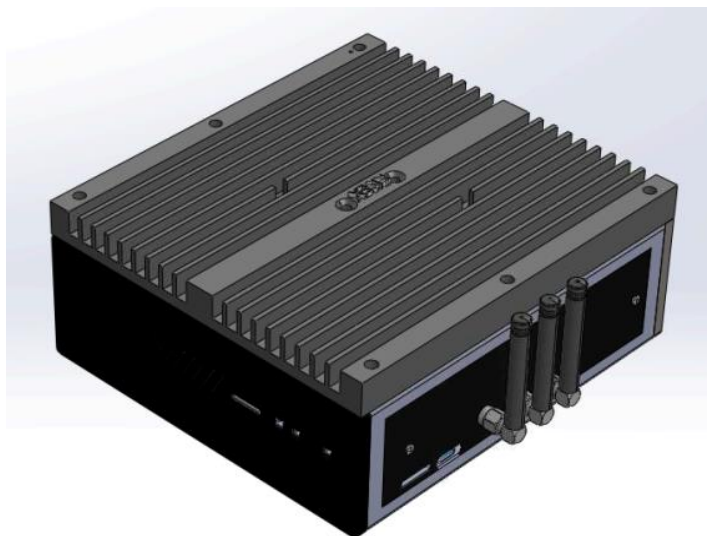
ADAS/DMS

Collision Detection: Vehicle | Pedestrian
Traffic Sign Detection
Drowsiness
Occupancy
Distraction
Seat Belt

Security & Surveillance

Intrusion Detection
Gun and Gunshot Detection
PPE Kit Detection
Activity Tracking
Fire and Smoke

Edge AI Box – Mechanical Images



HMI Expertise



Dual Display IVI System for Truck OEM (Design to Production)

The primary objective of this project is to develop and implement a custom control system for Heavy Duty Trucks, focusing on Human-Machine Interface (HMI) and service layers for both the Head-Unit Cluster and Head-Up Display. The system is designed to operate on Android 10 or greater and aims to enhance vehicle control, monitoring, and data visualization through an intuitive human-controlled interface.

Tech Stack: (CAN Data Acquisition Module)

- OS : Android 10
- Linux Kernel : 5.4
- Language: C
- Android 10
- Quectel's Android RIL Driver For Radio/Cellular Support
- NXP's Inbuilt Drivers for CAN, USB, USB hub, Wi-Fi/BLE and Gigabit Ethernet.
- Custom Driver Development for Temperature, Accelerometer, Gyrometer, Magnetometer, Light Sensor.



Tejas Android Infotainment System

Tejas Infotainment is a cutting-edge **IoT-enabled Smart HMI/UI Solution** that offers high-end display interface and seamless connectivity to drive a Premium User Experience. It gets its processing power from **Qualcomm 625** having 16GB eMMC and 2GB LPDDR3 memory and state of art firmware capabilities with **Android 9.0**. Being focused on IoT based Applications, Tejas TM Infotainment Solution carries wireless technology (**LTE, WiFi, BLE**) provisions as well as inbuilt **GPS, Microphone, and Speaker**.

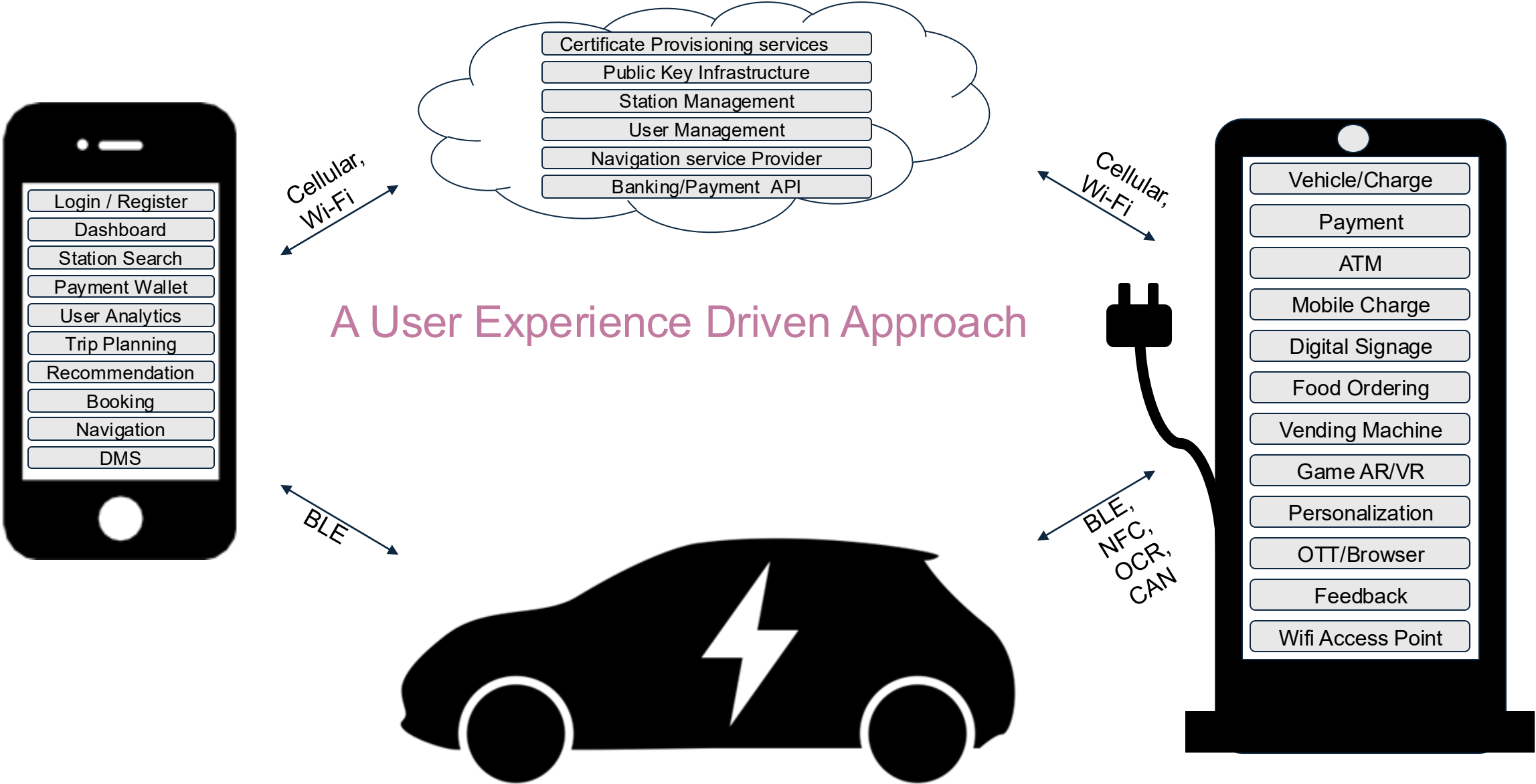
Specifications:

- SOM Board Dimension : 60mm x 60mm x 5mm
- GPU: Adreno 506 with 64-bit addressing
- SOC: Quectel SC600T (Qualcomm 625)
- Charging Type: USB TYPE C. Build-in Charge IC & Fuel Gauge, Qualcomm Quick Charge 3.0 technology
- Temperature Range: -25°F to 167°F
- WiFi: 2.4G/5G, 802.11 a/b/g/n/ac
- BLE: BT2.1+EDR/3.Q/4.1 LE/4.2 BLE
- External Storage: 256GB SD Card
- SOM Certification: CE/FCC/UL

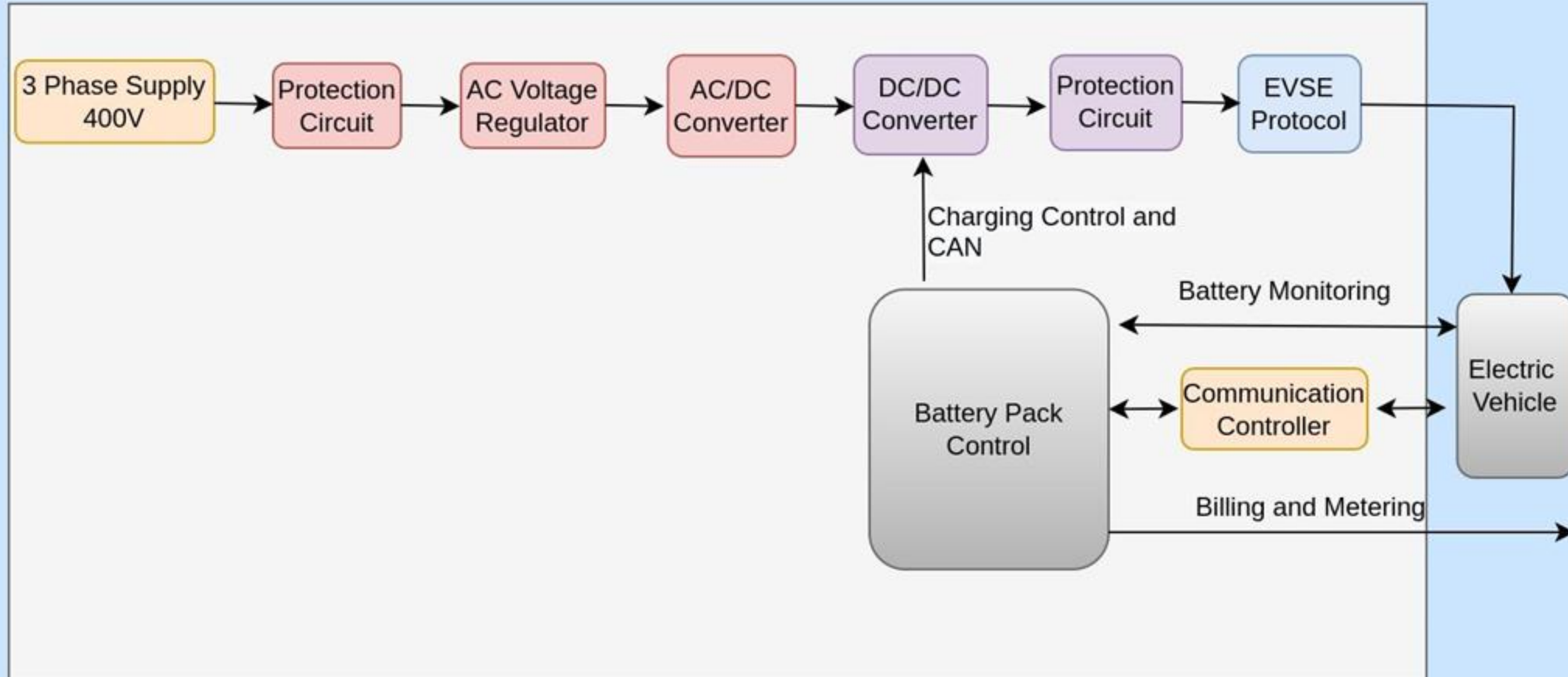


Concepts Built By Rapidise

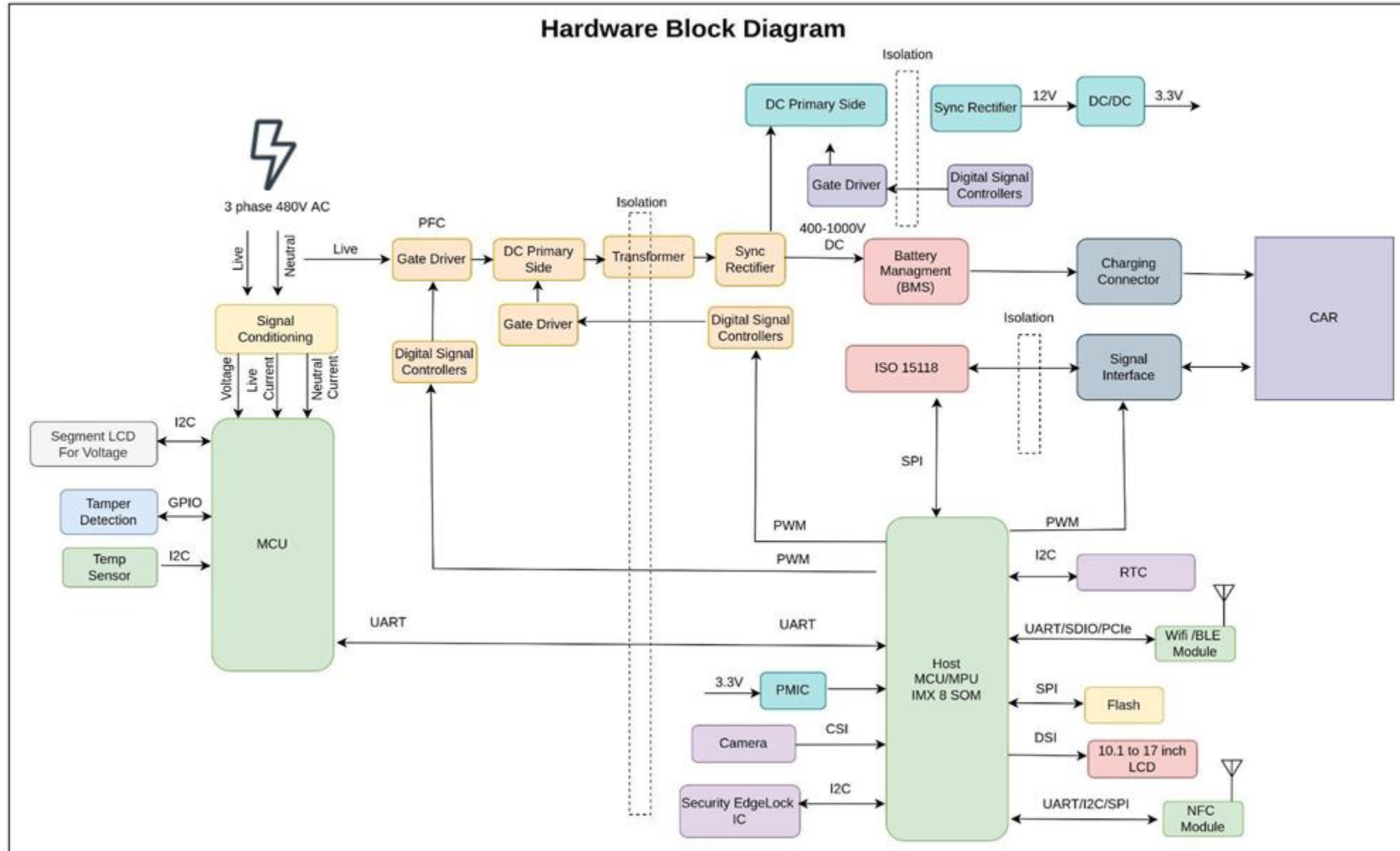




EV Station Top Level System Block Diagram



EV Charging Ecosystem – Hardware Block Diagram



Description of the system:

- **Input Voltage** : 415VAC, 3-phase / L1, L2, L3,N, Earthing
- **Signal conditioning** : Voltage,current measurement, Surge protection, Over voltage and Overcurrent protection
- **MCU** : Tamper detection feature, Voltage display on segment LCD, Internal temp sensor
- **Gate Driver** : Gate Driver for SiC MOSFETs/IGBTs
- **Transformer**: To boost the input voltage to required voltage
- **Sync Rectifier** : convert AC voltage to DC voltage
- **BMS** : calculate output current, protect the battery from short circuit, over voltage
- **Charging Connector**: Charging connector based on country and level of charger.
- **Signal Interface**: communication between Car and charging station
- **ISO 15118** : is an international standard that outlines the digital communication protocol that an electric vehicle (EV) and charging station should use to recharge the EV's high-voltage battery
- **Host MPU** : control Display, wireless connectivity, Camera, connect with our mobile
- **Security EdgeLock IC** : Supports compliance to many security standards like IEC 62443, DLMS/COSEM, OPC-UA and ISO15118-2, Real end-to-end security, from edge to cloud
- **NFC Module** : Contactless EV charging card solution based on MIFARE allows customers to pay easily, quickly and securely at the charging station.
- System will use below part to support 60KW capacity
 - Silicon Carbide MOSFETs, Silicon Carbide Schottky Diodes
 - High voltage and capacity IGBT for converting AC to DC.
 - High frequency/Power transformer



**IoT Product
Engineering**



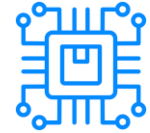
**Artificial Intelligence
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**PCBA & Full
Product Assembly**



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